

# INNOVATION MAXIMIZATION

**innomax**

**innomax**

**INNO - MAX CO.,LTD.**

**Head Office & Factory**

26 - 19, Songjeong - Ro 210beon - gil, Mado - Myeon, Hwaseong - Si, Gyeonggi - Do, Korea 445 - 862

TEL : +82 - 31 - 366 - 9631 / FAX : +82 - 31 - 366 - 9632 / [www.inno-max.co.kr](http://www.inno-max.co.kr)



**WORLD BEST  
TOTAL SOLUTION**  
IN.SEMICONDUCTOR.INDUSTRY

## OVERVIEW

INNO-MAX has been working and developing with customers and aims to be the best supplier in Semiconductor industry.

Every employee in INNO-MAX makes best efforts for the customers' satisfaction.

We devote, day and night, extensively to research, develop and provide the advanced solutions, bleeding-edge technologies and the best services support to exceed the customers' expectation in advance.

With more than 20 years experiences and Know-How in the semiconductor market, we promise to put our maximum efforts and passions into our products in return for our customers trust.

INNO-MAX will be always with you!

REPRESENTATIVE

## MANAGEMENT PHILOSOPHY

“Maximization of Customers Satisfaction with Continuous Innovation ”

## CORE VALUE



INNOVATION



PARTNERSHIP



QUALITY



RESPECT

## INNOMAX HISTORY

### 2016~2020

- 2020. 04 Development of 3Generation Spin Chuck
- 2018. 02 Turn - key Project for New Fab Line (6 Set, Singapore)

### 2006~2010

- 2010. 04 Development of 12"Spin Scrubber
- 2009. 10 Development of 12"Spin Etcher & Cleaner
- 12 Development of 12"FluxCoater & Flux Cleaner
- 2008. 01 INNOBIZ Company Certification
- 2006. 01 Venture Certification

### 2011~2015

- 2013. 07 Award Appreciation Plaque from Fair Child Korea
- 2012. 03 Exports of Cassetteless TRAUM to Japan Market (8Set)
- 10 Development of Marangoni Dryer (IMD TRAUM) 12" Pr-Strip
- 12 Development of 12" Metal Etcher (8chamber)
- 12 Promising Small & Medium Enterprise in Gyeonggi - Do(Korea) Award the 5 million dollar Export tower
- 2011. 07 Development of 8" Spin Lift-Off
- 09 Development of 12" Pr-Strip

### 2001~2005

- 2005. 03 Development of SPIN PROCESSOR
- 09 Coporate Firm INNOMAX Co.,Ltd
- 2002. 11 Development of WET STATION
- 2001. 01 Established of DSDM Co.

INNOMAX





3000 Series

# SINGLE SPIN PROCESSOR

ASTRO, Single wafer spin processor is a highly flexible wet processing platform, Designed for multiple applications for the most advanced semiconductor fabrication facilities



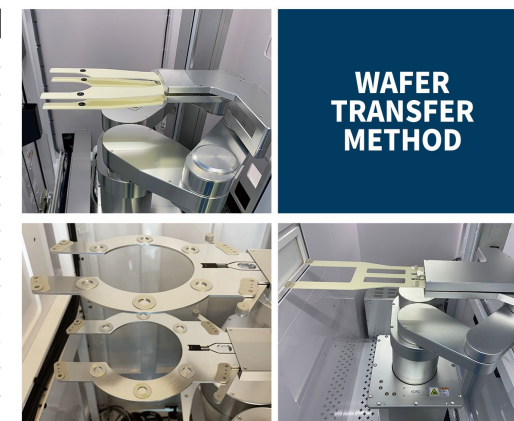
2000 Series

## Features

- Standard or customized design by customers' requirements
- High throughput & Small footprint
- Selective etching process for device-side or back-side
- Non-drip function to prevent recontamination
- Standby cleaning function to prevent crystallization of Dispenser inside
- Chemical "Recycle" or "One-shot drain" with chamber cup separation
- Provide various types of Spin Chucks
  - (Grip Chuck, Bernoulli Chuck, Venturi Chuck, Vacuum Chuck)
- Fully isolated wafer handling between before and after processing

## ASTRO Standard performance

ITEMS	DESCRIPTION
WAFER SIZE	~ 300mm [12"] Wafer
EQUIPMENT PERFORMANCE	MTBA : 48hrs
	MTTR : ≤ 4hrs
	MTBF : Min 500hrs
	UP-TIME : Min 90%
ES&H [SAFETY]	SEMI S2
	CE, S-Mark
CHAMBER	Up to 8Process Chambers [2 Layers type]
CHAMBER CHUCK [Option]	Vacuum, Grip, Bernoulli, Venturi
CHEMICAL SUPPLY	CCSS Supply [Max. 3 Chemicals]
CONTROL	Application : Visual GUI Package Pro-
	MS SQL Database
	Easy Analysis and Easy Maintenance
	User Definition



WAFER  
TRANSFER  
METHOD



300 Series  
Cassetteless type

# AUTO WET-STATION

TRAUM is the conventional wet station for various dipping processes such as Pre-diffusion, Cleaning, Etching, PR Strip Etc..

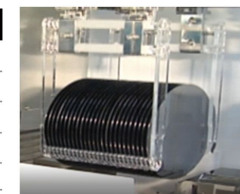


## Features

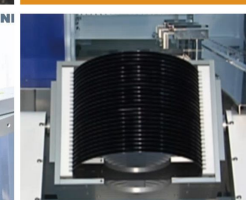
- INNO-MAX's own independent development equipment.
- Flexibility to process not only 300mm but also 200mm
- Standard or customized design by customers' requirements
- Patent wafer transfer robot for high throughput
- Reliable & User friendly software and hardware
- Short lead time through standardized design
- Low consumptions of DIW & Chemicals
- Two types of wafer transfer robot (Cassette & Cassetteless)

## TRAUM Standard performance

ITEMS	DESCRIPTION
WAFA SIZE	~ 300mm [12"] Wafer
	MTBA : 48hrs
	MTTR : ≤ 4hrs
EQUIPMENT PERFORMANCE	MTBF : Min 500hrs
	UP-TIME : Min 95%
CHEMICAL SUPPLY	CCSS Supply
ES&H [SAFETY]	SEMI S2
	CE,S-Mark
	Application : Visual GUI Package Program
	MS SQL Database
CONTROL	Easy Analysis and Easy Maintenance
	User Definition



WAFER  
REVERSE  
MOTION







200 Series  
Cassetteless type

# AUTO WET-STATION

TRAUM is the conventional wet station for various dipping processes such as Pre-diffusion, Cleaning, Etching, PR Strip Etc..

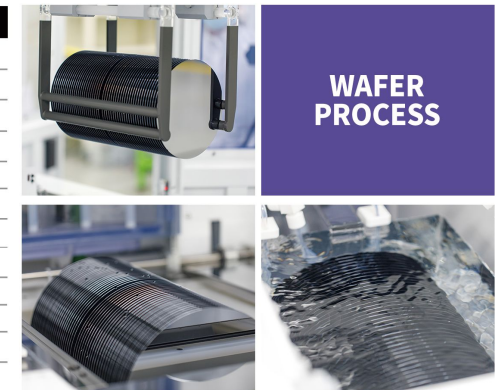


## Features

- Standard or customized design by customers' requirements
- Patent wafer transfer robot for high throughput
- Diverse experiences in Fab turn-key projects (Domestic & Oversea)
- Reliable & use friendly software and hardware
- Short lead time through standardized design
- Low consumptions of DIW & chemicals
- Two types of wafer transfer robot (Cassette & Cassetteless)

## TRAUM Standard performance

ITEMS	DESCRIPTION
WAFA SIZE	~ 200mm [8"] Wafer
	MTBA : 48hrs
	MTTR : ≤ 4hrs
EQUIPMENT PERFORMANCE	MTBF : Min 500hrs
	UP-TIME : Min 95%
CHEMICAL SUPPLY	CCSS Supply
ES&H [SAFETY]	SEMI S2
	CE,S-Mark
	Application : Visual GUI Package Program
CONTROL	MS SQL Database
	Easy Analysis and Easy Maintenance
	User Definition



WAFA  
PROCESS



## WAFER SORTER

### Features

- Fully automated wafer handling
  - ▶ Recipe-driven system (GUI)
- Customized recipe management
  - ▶ Sort, split, gather function etc.
- Small footprint
- Standard alone or Inline system
- Dual arm robot for maximum throughput
- Compatible for FOUP, FOSB and various
- Cassette type ( 200mm-> 300mm )
- Configurable load ports (Up to 4 load ports)
- State-of-the-art OCR (bottom or top side)



## CASSETTE CLEANER

### Features

- Stand Alone Type
- Temperature capability
  - 1)DIW : Up to 90°C
  - 2)AIR : Up to 150°C
  - ▶ Can be improved depending on required process
- Spin Capability
  - 1)During the Spray cleaning : Up to 10 RPM
  - 2)During the Drying process : Up to 110 RPM
- Particles
  - 1) 4 added per in<sup>2</sup> on carrier

## SPIN LAB SERIES

### Features

- Different size of wafers can be processed (Options)
- Possible to apply multi chemical in one chamber (3 Chemicals)
- Manual wafer loading or Automatic wafer loading (options)
- Up to 450mm wafer & mask (Thickness : 100µm~)
- Customized design is possible to meet customer's requirements
  - ▶ Standard & Optional Nozzle (Nano, High pressure, Flux, Etc..)
- Provide various types of Spin Chucks
  - ▶ Vacuum Chuck, Bernoulli chuck, Venturi Chuck, Grip Chuck

### Target Markets

- QA or R&D Laboratories
- Pilot production lines
- University / Institutes

